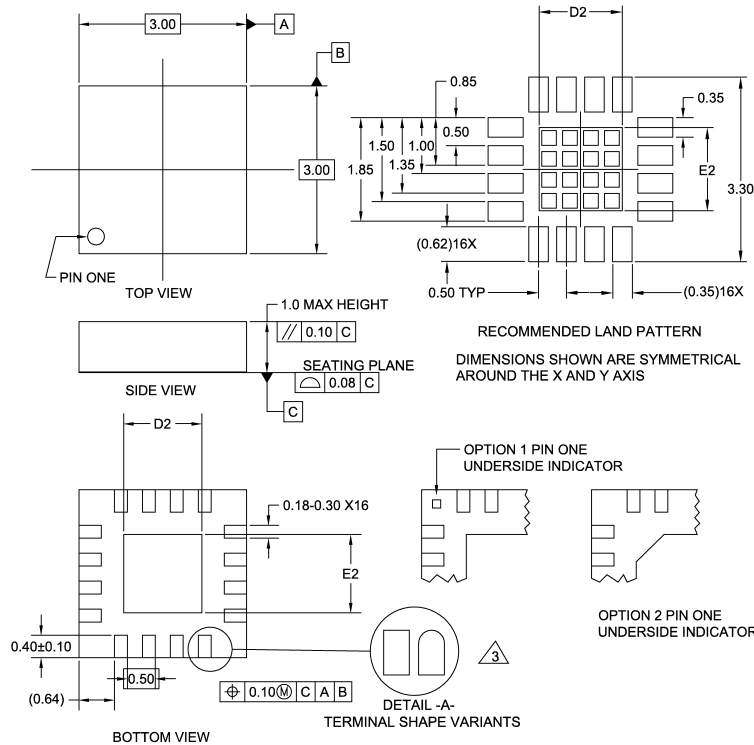


MLP16C



1. Package conforms to JEDEC MO-220
2. DIMENSIONS ARE IN MILLIMETERS
3. TERMINAL SHAPE MAY VARY ACCORDING TO PACKAGE SUPPLIER, SEE DETAIL A

DWG OPTION	DIM D2	DIM E2	TOLERANCE
01	1.40MM	1.40MM	+/- 0.10MM
02	1.50MM	1.50MM	+/- 0.10MM

MLP016CrevB

**16-Terminal Molded Leadless Package (MLP), JEDEC MO-220, 3mm Square
Package Number MLP16C**

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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